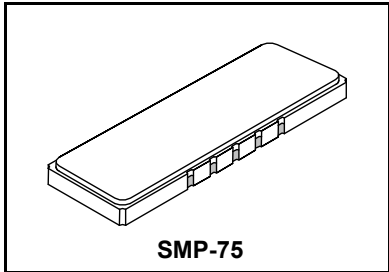


SF1088A

**170.6 MHz
SAW Filter**



- *Designed for GSM BTS Receiver IF Applications*
- *Low Insertion Loss*
- *Excellent Size-to-Performance Ratio*
- *Hermetic SMP-75 Surface-Mount Case*
- *Unbalanced Input and Output*
- *Complies with Directive 2002/95/EC (RoHS)*



Absolute Maximum Ratings

Rating	Value	Units
Maximum Incident Power in Passband	+10	dBm
Max. DC voltage between any 2 terminals	30	VDC
Storage Temperature Range	-40 to +85	°C
Suitable for lead-free soldering - Max. Soldering Profile	260°C for 30 s	

Electrical Specifications

Characteristic	Sym	Notes	Min	Typ	Max	Units
Nominal Center Frequency	f_c	1	170.600			MHz
Passband	Insertion Loss at fc 1 dB Passband	IL	1, 2	±90	8.0	dB
					Amplitude Ripple over $f_c \pm 90$ kHz	1.0
	Group Delay Variation over $f_c \pm 190$ kHz	GDV		<500	1000	ns _{P-P}
Rejection	fc-0.6 to fc-0.4 and fc+0.4 to fc+0.6 MHz		1, 2, 3	13	15	dB
	fc-0.8 to fc-0.6 and fc+0.6 to fc+0.8 MHz			27	35	
	fc-1.6 to fc-0.8 and fc+0.8 to fc+1.6 MHz			40	45	
	fc-3.0 to fc-1.6 and fc+1.6 to fc+3.0 MHz			43	55	
	fc-5.8 to fc-3.0 and fc+3.0 to fc+5.8 MHz			47	55	
	fc-35 to fc-5.8 and fc+5.8 to fc+35 MHz			50	55	
	fc-75 to fc-35 and fc+35 to 75 MHz			45	55	
	DC to fc-75 and fc+75 to fc+1000 MHz			40		
Operating Temperature Range	T _A	1	-10		+85	°C

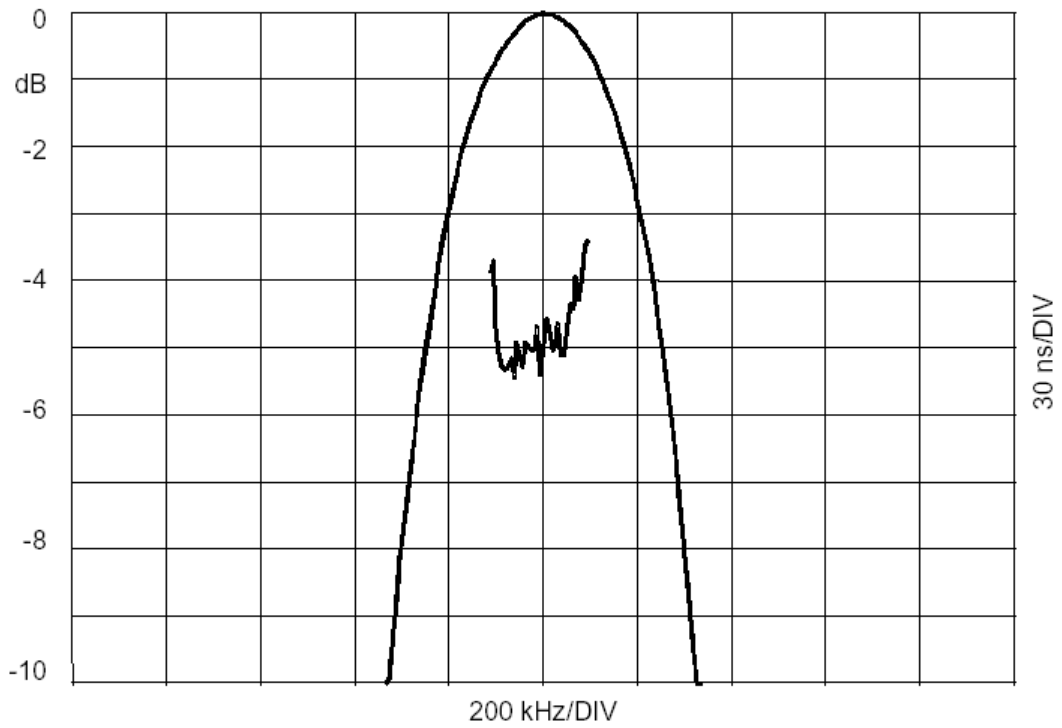
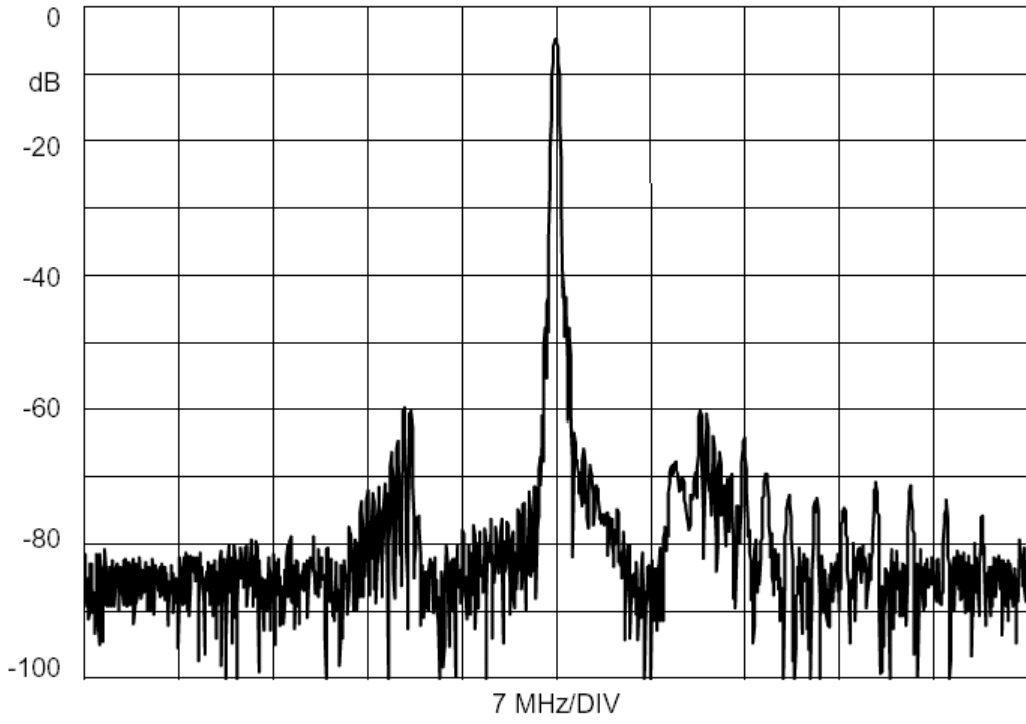
Impedance Matching to 50 Ω unbalanced	External L-C
Case Style	SMP-75 19 x 6.5 mm Nominal Footprint
Lid Symbolization (YY = year, WW = week)	RFM SF1088A YYWW



CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.

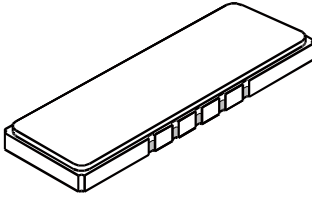
NOTES:

1. Unless noted otherwise, all specifications apply over the operating temperature range with filter soldered to the specified demonstration board with impedance matching to 50 Ω and measured with 50 Ω network analyzer.
2. Unless noted otherwise, all frequency specifications are referenced to the nominal center frequency, f_c .
3. Rejection is measured as attenuation below the minimum IL point in the passband. Rejection in final user application is dependent on PCB layout and external impedance matching design. See Application Note No. 42 for details.
4. "LRIP" or "L" after the part number indicates "low rate initial production" and "ENG" or "E" indicates "engineering prototypes."
5. The design, manufacturing process, and specifications of this filter are subject to change.
6. Either Port 1 or Port 2 may be used for either input or output in the design. However, impedances and impedance matching may vary between Port 1 and Port 2, so that the filter must always be installed in one direction per the circuit design.
7. US and international patents may apply.



SMP-75 Case

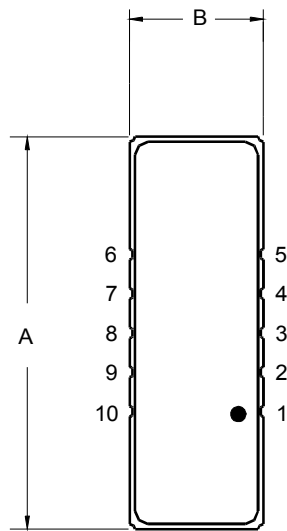
10-Terminal Ceramic Surface-Mount Case 19 x 6.5 mm Nominal Footprint



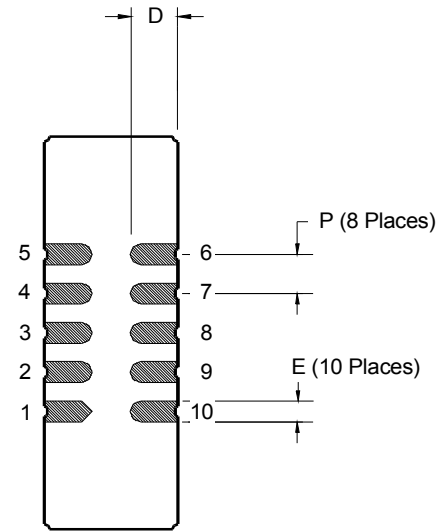
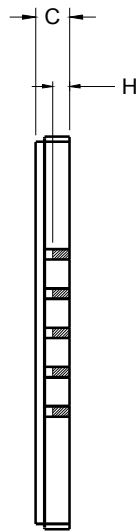
Case Dimensions						
Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	18.80	19.00	19.30	0.740	0.748	0.760
B	6.30	6.50	6.80	0.248	0.256	0.268
C		1.75	2.00		0.069	0.079
D		2.29			0.090	
E		1.02			0.040	
H		1.0			0.039	
P		1.905			0.075	

Materials	
Solder Pad Termination	Au plating 30 - 60 μ inches (76.2-152 μ m) over 80-200 μ inches (203-508 μ m) Ni.
Lid	Fe-Ni-Co Alloy Electroless Nickel Plate (8-11% Phosphorus) 100-200 μ inches Thick
Body	Al ₂ O ₃ Ceramic
Pb Free	

Electrical Connections		
Connection		Terminals
Port 1	Input or Return	10
	Return or Input	1
Port 2	Output or Return	5
	Return or Output	6
Ground		All others
Single Ended Operation		Return is ground
Differential Operation		Return is hot



TOP VIEW



BOTTOM VIEW